



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

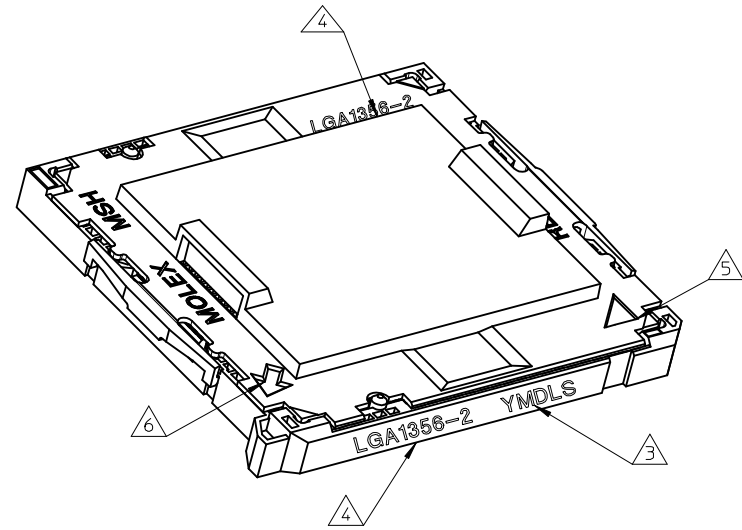
SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

- 3. DATE-CODE LOCATION. AND DATE-CODE *YMDLS* IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)
- 4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

5. SOCKET PIN 1 INDICATOR.

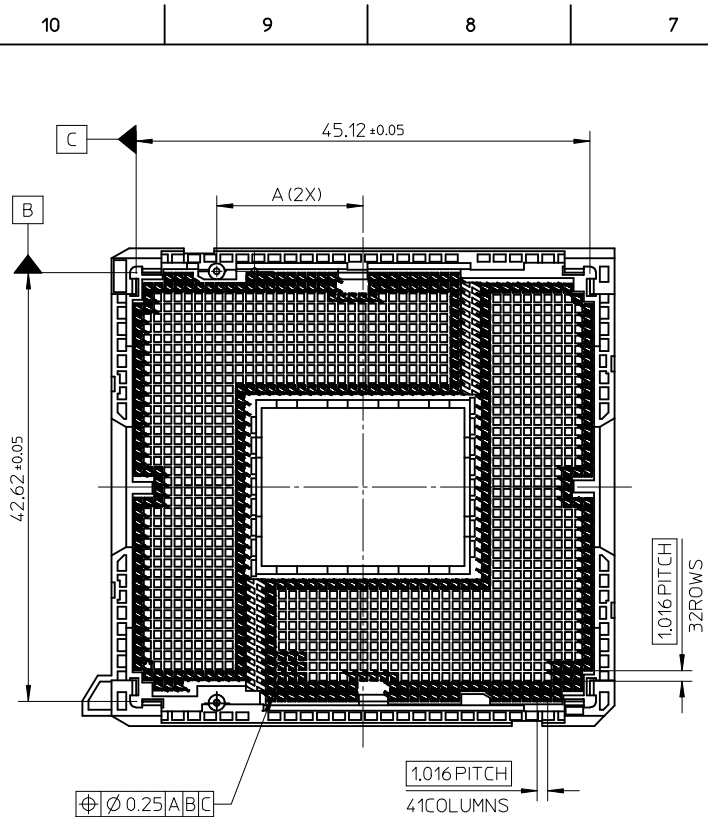
6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

- 7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.
- 8. PRODUCT PACKAGE PK-47594-003 APPLIES.
- 9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

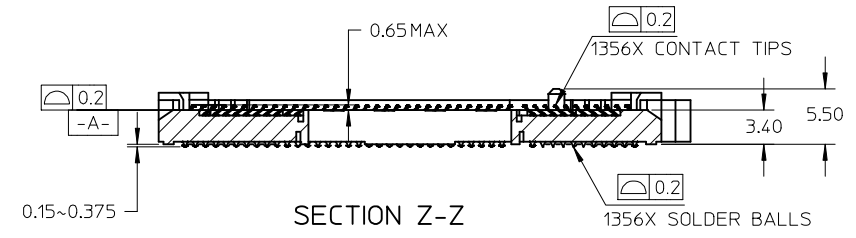
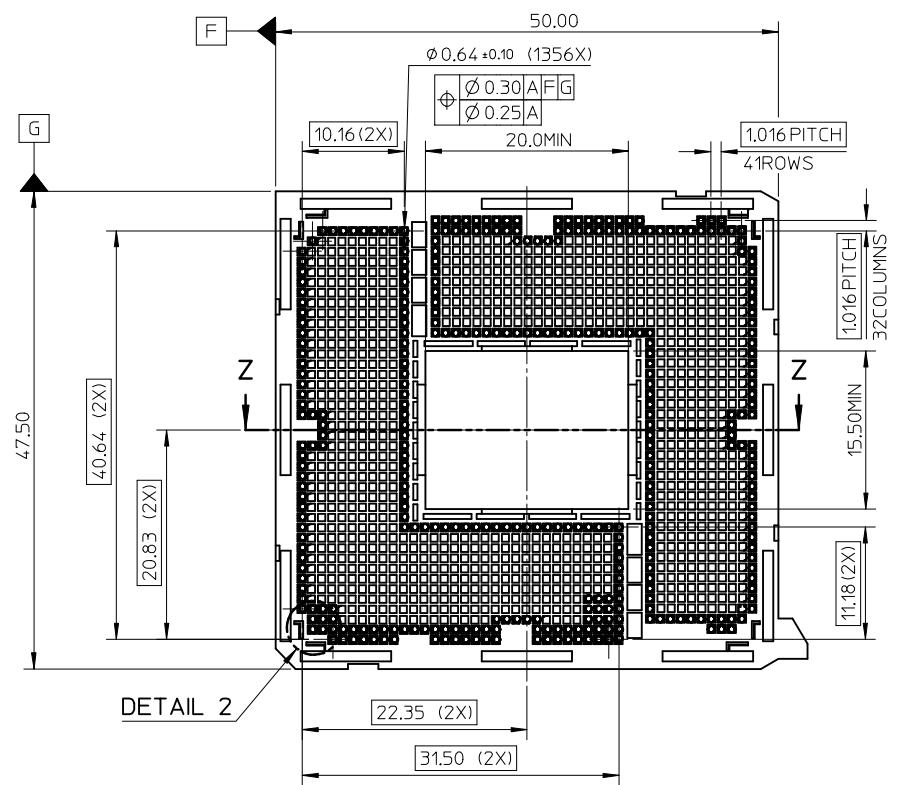
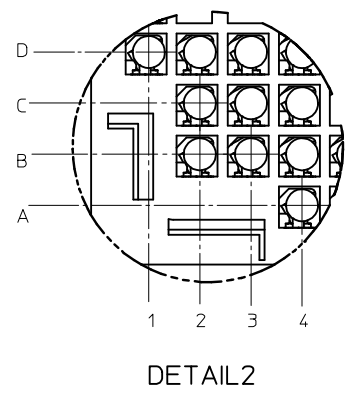


LGA1356 SOCKET PART NUMBER LIST					PART NAME	REMARK
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT		
475943001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-2(B2)	DIM.A=12.85
475943002	GENERAL	30u*(0.76um)				

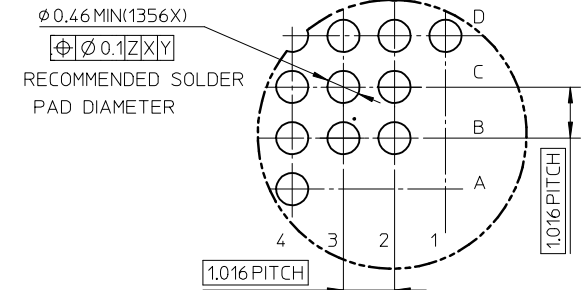
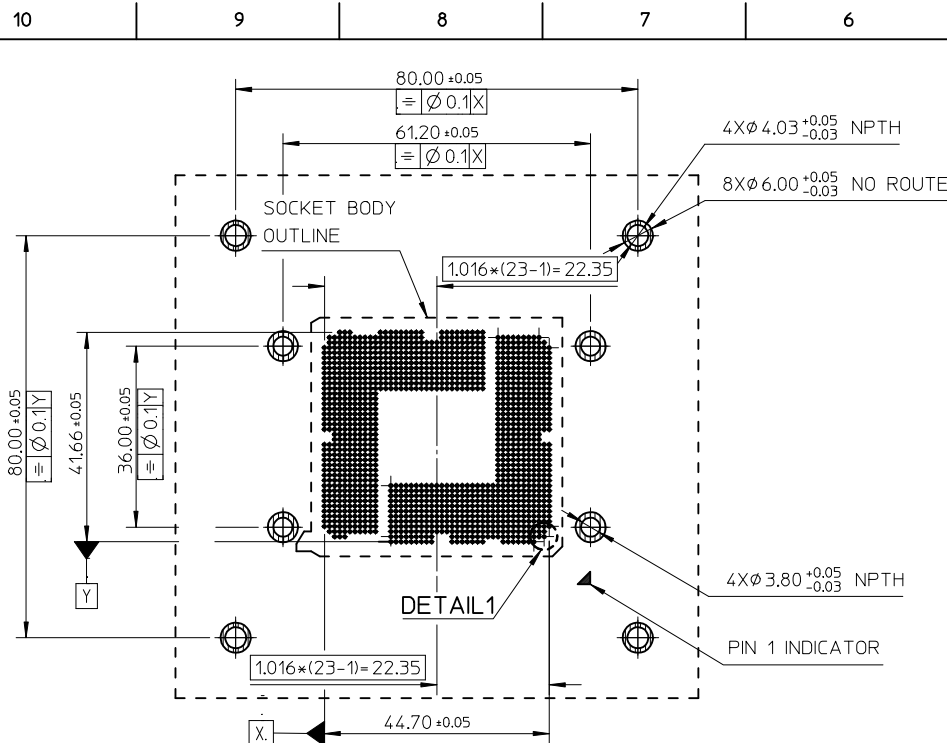
RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$F_A=0$ $F_C=0$ $F_B=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1°	MM ONLY	2:1	METRIC	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE JZHANG11 2010/2/10 CHECKED BY DATE APPROVED BY DATE AYIN 2011/07/12	TITLE LGA1356 SOCKET FULL ASSEMBLY		
			MATERIAL NO. SEE TABLE SIZE A3	MOLEX INCORPORATED DOCUMENT NO. SD-47594-100		SHEET NO. 1 OF 3



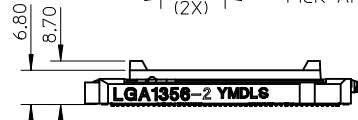
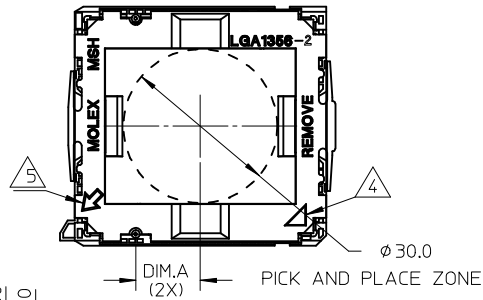
1356X CONTACT POINTS FOR PACKAGE LAND



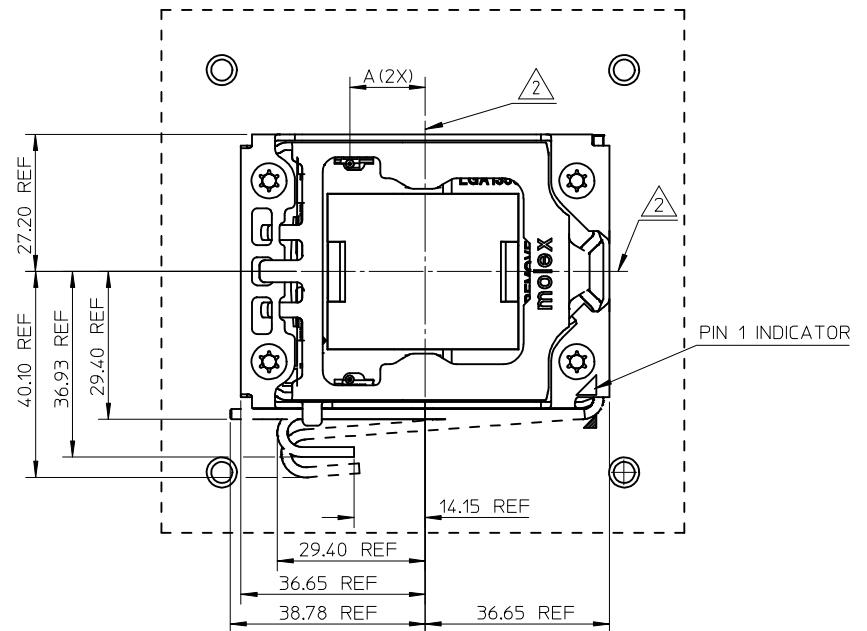
RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $\nabla_{\text{A}} = 0$ $\nabla_{\text{B}} = 0$ $\nabla_{\text{C}} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± 0.25	± ---	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	± ---	± ---																		
	3 PLACES	± ---	± ---																		
2 PLACES	± 0.20	± ---																			
1 PLACE	± 0.25	± ---																			
		DRAWN BY: JZHANG11 DATE: 2010/2/10 CHECKED BY:	TITLE LGA1356 SOCKET FULL ASSEMBLY	MOLEX INCORPORATED																	
		APPROVED BY: AYIN DATE: 2011/07/12	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-47594-100	SHEET NO. 2 OF 3																
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	



RECOMMEND PCB LAYOUT THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
 - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
 - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 - SOCKET PIN 1 INDICATOR.
 - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
 - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.



RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $\nabla_F=0$ $\nabla_E=0$ $\nabla_D=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES	\pm ---	\pm ---	DRAWN BY JZHANG11	DATE 2010/2/10	TITLE LGA1356 SOCKET FULL ASSEMBLY
		3 PLACES	\pm ---	\pm ---	CHECKED BY	DATE	
		2 PLACES	± 0.20	\pm ---	APPROVED BY AYIN	DATE 2011/07/12	MATERIAL NO.
		1 PLACE	± 0.25	\pm ---			MOLEX INCORPORATED
		ANGULAR $\pm 1^\circ$		SEE TABLE		DOCUMENT NO. SD-47594-100	SHEET NO. 3 OF 3
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

3. DATE-CODE LOCATION, AND DATE-CODE "YMDLS"
 IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)

4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

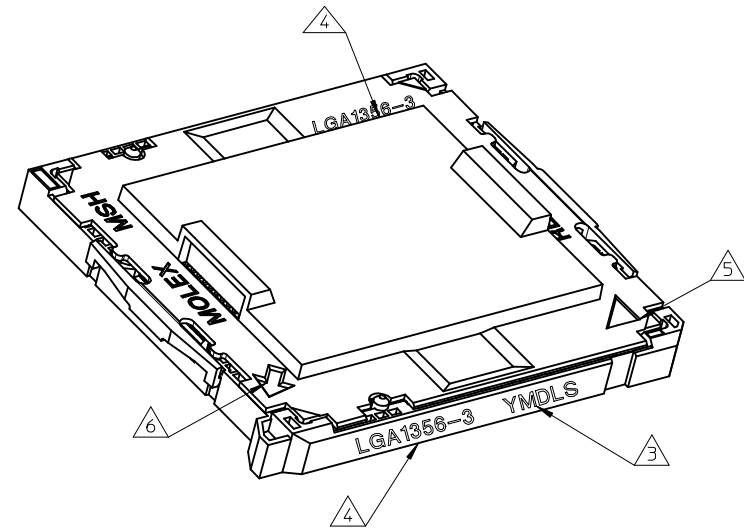
5. SOCKET PIN 1 INDICATOR.

6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

8. PRODUCT PACKAGE PK-47594-003 APPLIES.

9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS
 DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

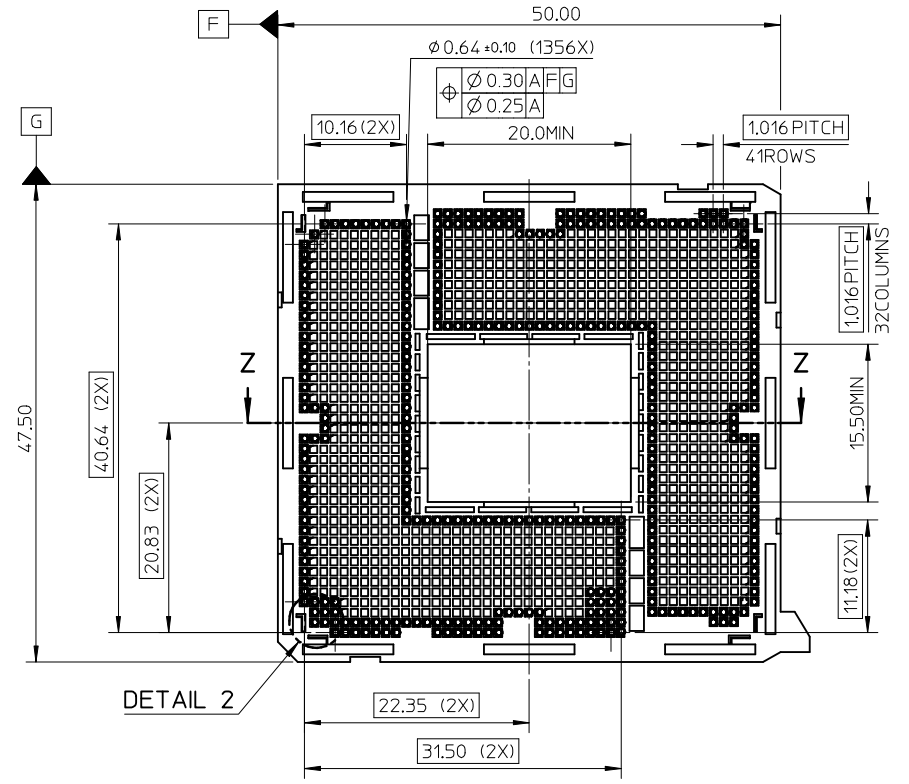
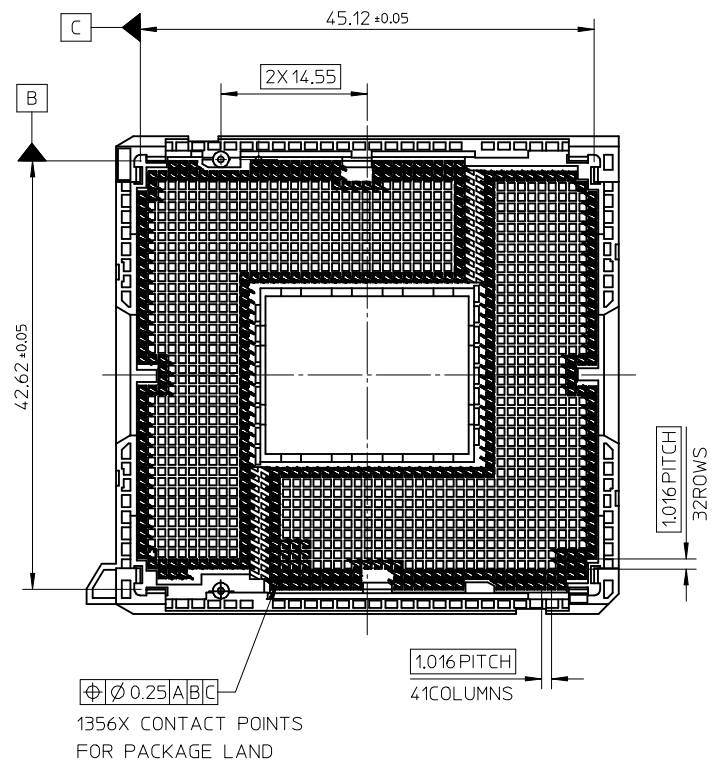


LGA1356 SOCKET PART NUMBER LIST					PART NAME
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT	
475942001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-3(B3)
475942002	GENERAL	30u*(0.76um)			

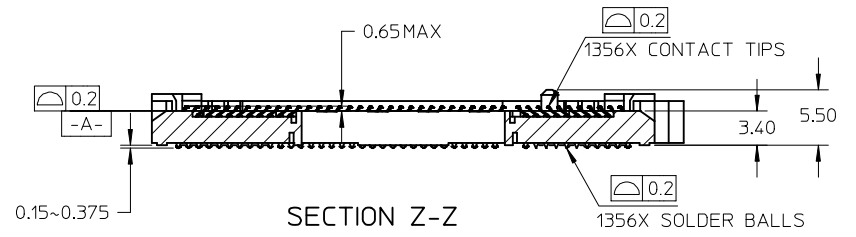
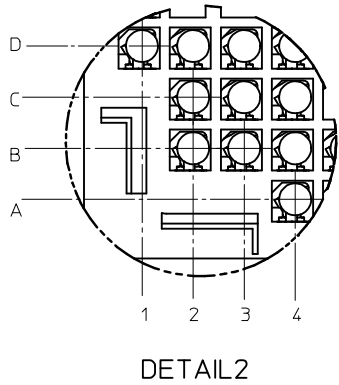
NEW RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/09/24 CH'KD: APPR: AYIN 2013/02/04 REV 1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	$F_{\square}=0$	mm	INCH	MM ONLY	2:1	METRIC		
	$F_{\square}=0$	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE		LGA1356-3 SOCKET(B3) FULL ASSEMBLY
	$F_{\square}=0$	2 PLACES ± 0.20 ± ---	1 PLACE ± 0.25 ± ---	0 PLACE ± --- ± ---	YXZHENG	2012/09/24		
	ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY	DATE	molex		
	SEE TABLE		MATERIAL NO.		DOCUMENT NO.	SHEET NO.		
	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SD-47594-200		1 OF 3	

10 9 8 7 6 5 4 3 2 1

F E D C B A

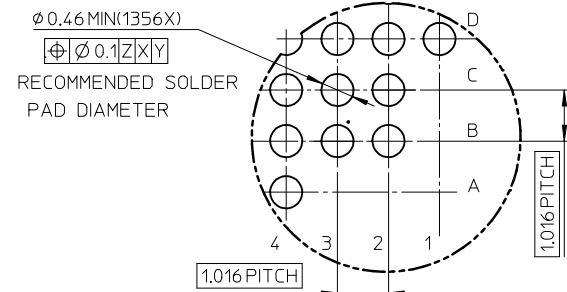
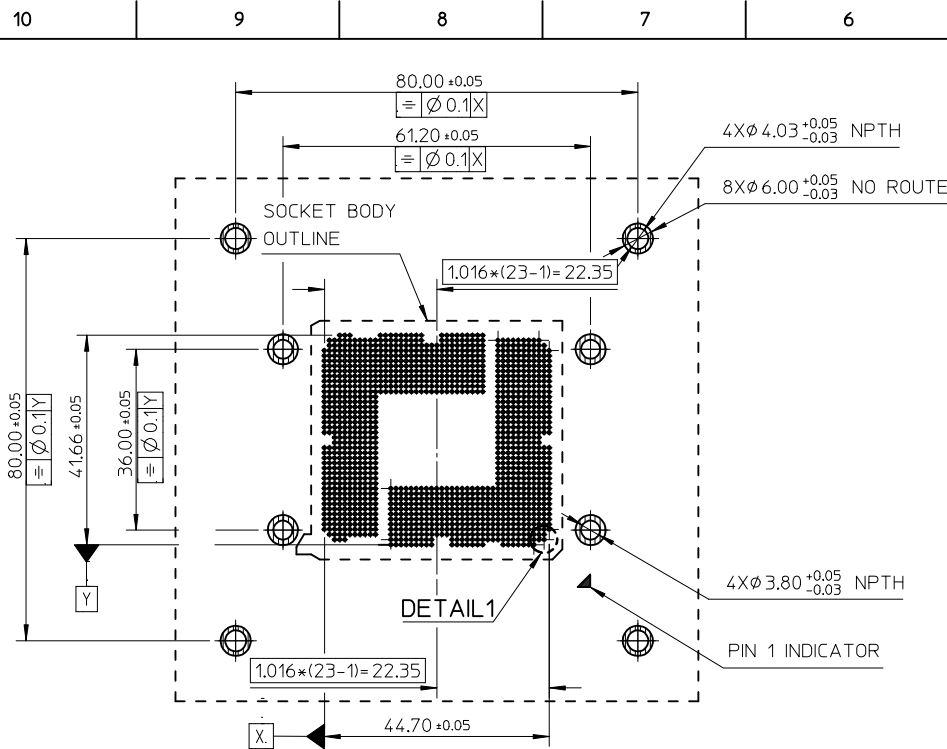


DETAIL 2

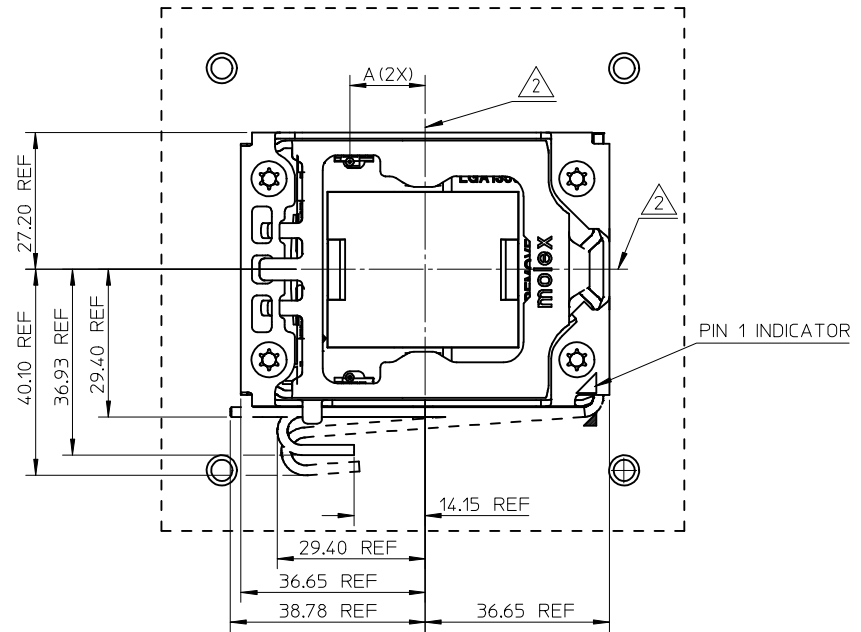


NEW RELEASED EC NO: SHZ013-0064 DRWN: YXZHENG 2012/09/24 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $F_A=0$ $F_B=0$ $F_C=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± --- ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY DRAWN BY: YXZHENG CHECKED BY: APPROVED BY: AYIN DATE: 2012/09/24 DATE: DATE: 2013/02/04	SCALE 2:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY molex DOCUMENT NO. SD-47594-200 SHEET NO. 2 OF 3
	SEE PAGE 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	SIZE A3				

9 8 7 6 5 4 3 2 1

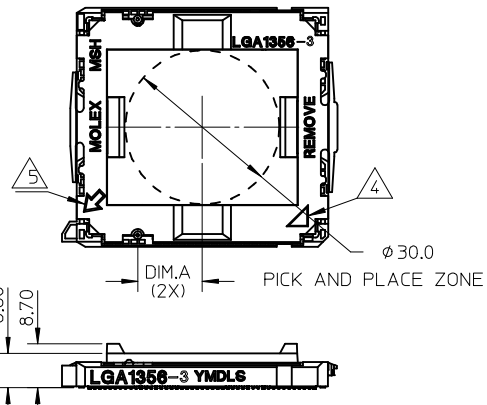


DETAIL1
SCALE 10:1



SOCKET ON PCB(FOR REFERENCE ONLY)
LOAD PLATE IS NOT LOCKED

RECOMMEND PCB LAYOUT
THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
 - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
 - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 - SOCKET PIN 1 INDICATOR.
 - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
 - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.

NEW RELEASED IEC NO: SH2013-0064 DRWN: YXZHENG CHKD: APPR: AYIN 2012/09/24 2013/02/04	QUALITY SYMBOLS $F_{\square} = 0$ $F_{\square} = 0$ $F_{\square} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	mm INCH	DRAWN BY YXZHENG	DATE 2012/09/24	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY AYIN	DATE 2013/02/04	molex			
		ANGULAR ± 1 °		MATERIAL NO. SEE PAGE 1		DOCUMENT NO. SD-47594-200	SHEET NO. 3 OF 3		